

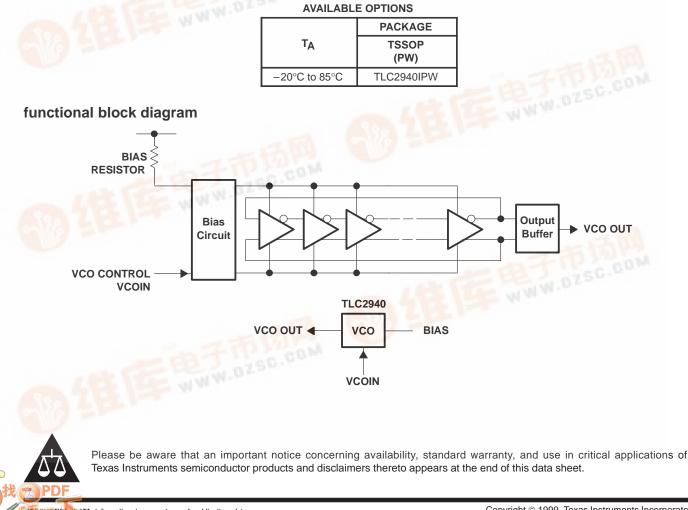
- 8-Pin Thin Shrinked Small-Outline Package

description

The TLC2940 is a high-performance analog voltage-controlled oscillator (VCO) using Texas Instruments 0.8-µm CMOS process. The VCO oscillating operation can be performed by an external bias resistor connected to the internal oscillation circuitry, and the oscillation frequency range is set by this bias resistor. The lock frequency range for PLL applications is from 35 MHz to 75 MHz (over operating free-air temperature range, V_{DD} = 5 V ± 5%), and from 28 MHz to 50 MHz (over operating free-air temperature range, V_{DD} = 3 V ± 5%). The stable analog PLL can be configured within these frequency ranges.

The device is available in an 8-pin TSSOP surface-mount package.

The PLL block is configured using a counter, a required LPF, and a phase frequency detector (PFD).





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Terminal Functions

TERMINAL		t	DESCRIPTION			
NAME	NO.	1/O†	DESCRIPTION			
BIAS	7	М	Bias supply terminal for internal VCO. The resistor should be located between V_{DD} and this terminal.			
FREFINPUT	3	1	Not used. This terminal should be tied to ground.			
GND	5	PS	Ground			
LOGIC V _{DD}	1	PS	Power supply for the internal logic circuitry (PFD portion, input/output portion). It is recommended that this terminal is separated from the VCO supply voltage terminal.			
PFD OUT	4	0	Not used. This terminal should be unconnected (open).			
VCOIN	6	1	VCO control voltage input.			
VCO OUT	2	0	VCO output. This terminal is tied to a low level at inhibit status.			
VCO V _{DD}	8	PS	Supply voltage for VCO analog portion.			

[†] I: Input, O: Output, PS: Power supply/GND, M: Others

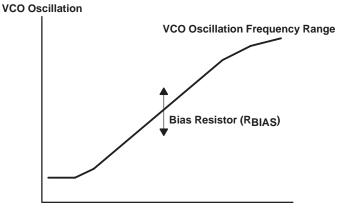
detailed description

The TLC2940 is an analog VCO IC that generates a frequency that is a multiple of a reference frequency for a PLL block configuration. Normally, a PLL block is composed of a VCO, a phase frequency detector, counter logic, and a loop filter.

The following is a description for the analog VCO of the TLC2940.

The built-in analog VCO is composed of a ring oscillator portion for oscillation operation and a bias control portion to generate a bias level to supply to the ring oscillator. The oscillation operation is performed by a bias resistor (R_{BIAS}) connected between the bias control (pin 7) and the supply voltage (pin 8). The VCO oscillation frequency is determined by this resistor value, R_{BIAS}, that is, the oscillation frequency decreases as the resistor value increases, and the oscillation frequency increases as the resistor value decreases. The lock frequency range is from 35 MHz to 75 MHz with a R_{BIAS} of 1.5 k Ω to 4.3 k Ω at 5-V operation and from 28 MHz to 50 MHz with a R_{BIAS} of 1.5 k Ω to 2.7 k Ω at 3-V operation over the recommended supply voltage and operating free-air temperature range.

Refer to the curves shown in the typical characteristics section for the lock frequency ranges with varying $\mathsf{R}_{\mathsf{BIAS}}$ values.



VCO Control Voltage (VCOIN)

Figure 1. VCO Oscillation Frequency Range Setting



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage (any supply), V _{DD} (see Note 1)	
Input voltage range (any input), VI (see Note 1)	
Input current (any input), I	±20 mA
Output current (any output), I _O	±20 mA
Continuous total power dissipation ($T_A = 25^{\circ}C$ or below), P_D (see Note 2)	
Operating free-air temperature range, T _A	$\dots \dots -20^{\circ}C$ to $85^{\circ}C$
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network GND terminals.

2. For operation above 25°C free-air temperature, derate linearly at the rate of 5.6 mW/°C.

recommended operating conditions

PARAMETER				NOM	MAX	UNIT	
Supply voltage $V_{}$ (any supply and Notes 2 and 4)	3-V operation		2.85	3	3.15	V	
Supply voltage, V_{DD} (any supply, see Notes 3 and 4)	5-V operation	4.75	5	5.25			
Input voltage, VI (inputs except VCO IN)			0		V _{DD}	V	
Output current, IO (any output)			0		±2	mA	
VCO control voltage at VCO IN			1		V _{DD} -0.5	V	
		$R_{BIAS} = 1.5 \text{ k}\Omega$	42		50		
	3-V operation	$R_{BIAS} = 1.8 \text{ k}\Omega$	37		47		
		$R_{BIAS} = 2.2 \text{ k}\Omega$	33		45		
Look fraguesou		$R_{BIAS} = 2.7 \text{ k}\Omega$	28		42	MHz	
Lock nequency		$R_{BIAS} = 1.5 \text{ k}\Omega$	65		75	IVITIZ	
Lock frequency	5-V operation	$R_{BIAS} = 2.4 \text{ k}\Omega$	50		65		
		$R_{BIAS} = 3.3 \text{ k}\Omega$	43		56		
		$RBIAS = 4.3 k\Omega$	35		50		
	3-V operation		1.5		2.7	kΩ	
VCO oscillation frequency setting resistor, RBIAS	5-V operation				4.3	K22	
Operating free-air temperature, TA			-20		85	°C	

NOTES: 3. It is recommended that the logic supply terminal (LOGIC V_{DD}) and the VCO supply terminal (VCO V_{DD}) should be at the same voltage and separate from each other.

4. The bypass capacitor should be located as close as possible to each power supply.

5. The FREFINPUT (pin 3) and PFD OUT (pin 4) terminals are input/output terminals preset for logic function respectively. In normal operation, the FREFINPUT should be tied to GND and PDF OUT should be left unconnected (open).



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electrical characteristics over recommended operating free-air temperature range, V_{DD} = 3 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VOH	High-level output voltage, VCO OUT	$I_{OH} = -2 \text{ mA}$	2.4			V
VOL	Low-level output voltage, VCO OUT	I _{OL} = 2 mA			0.3	V
Z _{i(VCOIN)}	Input impedance at VCOIN	VCO IN = $1/2$ V _{DD}		10		MΩ
IDD(VCO)	Supply current	See Note 6		6	10	mA
fosc	Oscillation frequency	$R_{BIAS} = 2.4 \text{ k}\Omega, \text{ VCOIN} = 1/2 \text{ V}_{DD}$	32	40	48	MHz
tr	Output rise time	VCOIN = 0 V, R _{BIAS} =2.4 k Ω , CL = 15 pF		13		ns
t _f	Output fall time	VCOIN = 0 V, R _{BIAS} =2.4 k Ω , C _L = 15 pF		6		ns
	Output duty ratio	$R_{BIAS} = 2.4 \text{ k}\Omega$, VCOIN = 1/2 V_{DD} , See Note 7	40%	44%	60%	
α _(fosc)	Temperature coefficient of oscillation frequency	VCOIN = 1/2 V _{DD} , R _{BIAS} = 2.4 kΩ, T _A = -20° C to 85°C		0.07		%/°C
kSVS(fosc)	Supply voltage coefficient of oscillation frequency	VCOIN = 1.5 V, R _{BIAS} = 2.4 kΩ, V _{DD} = 2.7 V to 3.3 V		0.01		%/mV

NOTES: 6. VCOIN = $1/2 V_{DD}$, $R_{BIAS} = 2.4 k\Omega$, current through pin 1 and 8.

7. The maximum and minimum value of this parameter are not production tested.

electrical characteristics over recommended operating free-air temperature range, V_{DD} = 5 V (unless otherwise noted)

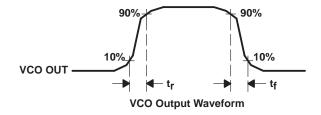
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VOH	High-level output voltage, VCO OUT	$I_{OH} = -2 \text{ mA}$	4.5			V
VOL	Low-level output voltage, VCO OUT	I _{OL} = 2 mA			0.5	V
Z _{i(VCOIN)}	Input impedance at VCOIN	$VCOIN = 1/2 V_{DD}$		10		MΩ
IDD(VCO)	Supply current	See Note 6		16	30	mA
fosc	Oscillation frequency	$R_{BIAS} = 2.4 \text{ k}\Omega, \text{ VCOIN} = 1/2 \text{ V}_{DD}$	45	65	85	MHz
t _r	Output rise time	VCOIN = 0 V, R _{BIAS} =2.4 k Ω , CL = 15 pF		5.8		ns
t _f	Output fall time	VCOIN = 0 V, R _{BIAS} =2.4 k Ω , C _L = 15 pF		3.2		ns
	Output duty ratio	$R_{BIAS} = 2.4 \text{ k}\Omega$, VCOIN = 1/2 V_{DD} , See Note 7	40%	46%	60%	
$\alpha_{(fosc)}$	Temperature coefficient of oscillation frequency	VCOIN = 1/2 V _{DD} , R _{BIAS} = 2.4 kΩ, $T_A = -20^{\circ}$ C to 85°C		0.06		%/°C
kSVS(fosc)	Supply voltage coefficient of oscillation frequency	VCOIN = 2.5 V, R _{BIAS} = 2.4 kΩ, V _{DD} = 4.5 V to 5.5 V		0.005		%/mV

NOTES: 6. VCOIN = $1/2 V_{DD}$, $R_{BIAS} = 2.4 k\Omega$, current through pin 1 and 8. 7. The maximum and minimum value of this parameter are not production tested.



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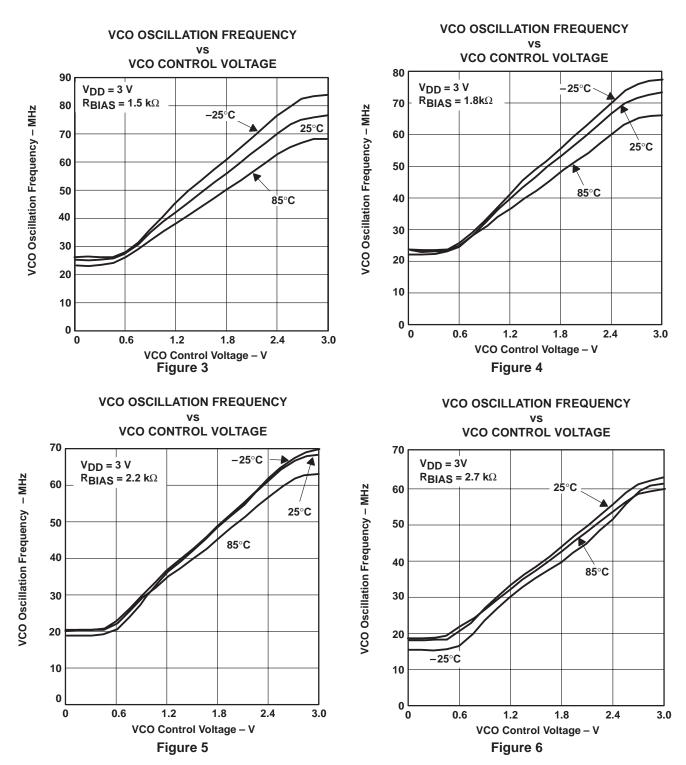
PARAMETER MEASUREMENT INFORMATION







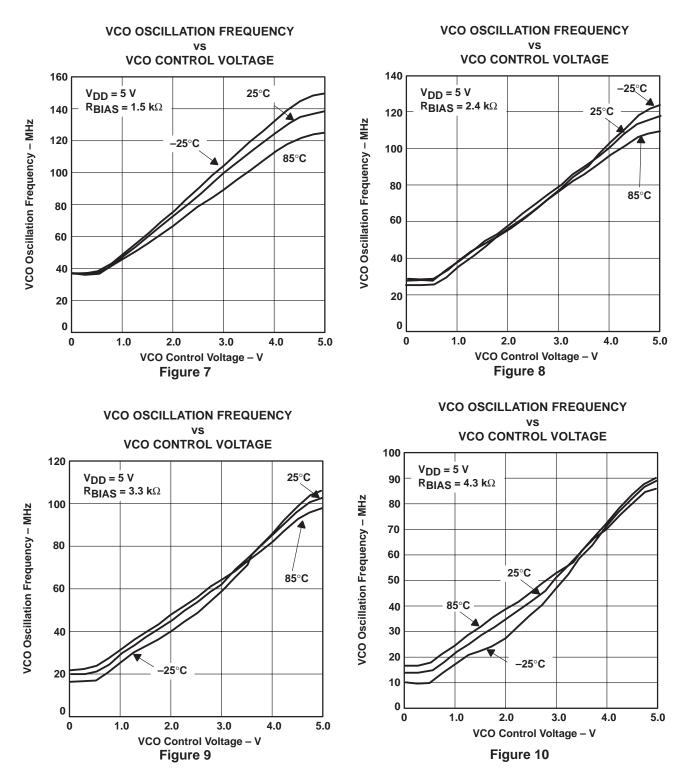
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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS

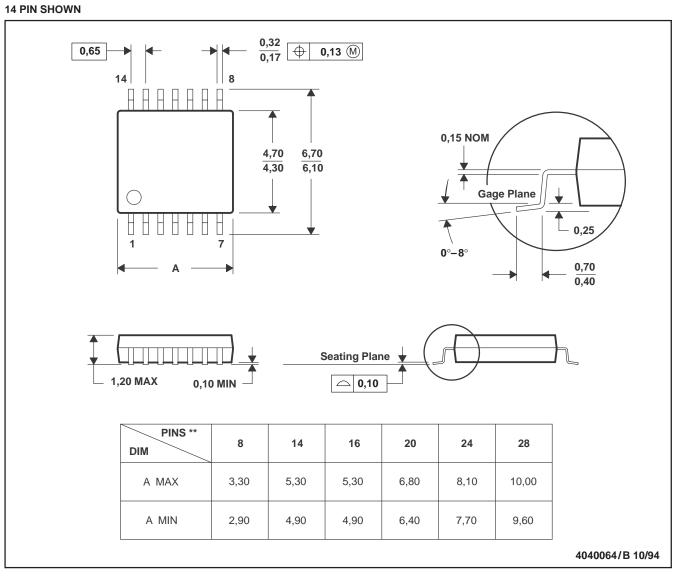


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PW (R-PDSO-G**)

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.



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